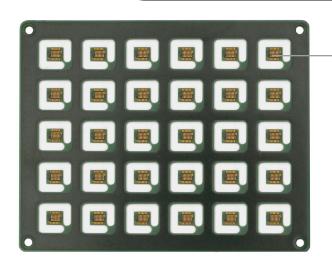
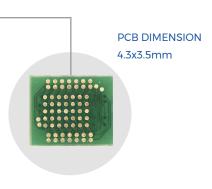
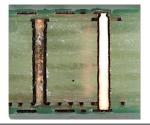


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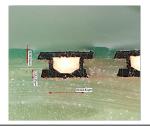
HDI PCB



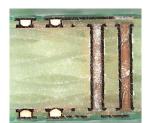




Buried holes Ø 0,15mm and vias resin filled and CU capped



Blind vias Ø 0,1mm with resin filled and CU capped



Buried holes Ø 0,15mm and blind vias Ø 0,12mm with resin filled and CU capped

OVERVIEW

HDI PCBs are a technologically advanced solution to reduce size, improve performance, and increase the reliability of modern electronic devices. The use of microvias, multilayer stack-ups, and innovative materials makes these PCBs essential for high-density and high-speed applications.

TECHNICAL DATA

TECHNOLOGY HDI PCBs TYPE: 4 layers BASE MATERIAL: HTg THICKNESS: 1mm PCB DIMENSION: 4.3x3.5mm MIN. FINISH HOLES: 0,12mm FINISHING: **ENIG** PLATING: 2 STEPS OF PLATING DRILL: 4 STEPS

OF DRILLING

TECHNOLOGY

HOLES

BURRIED VIAS RESIN FILLED AND CU CAPPED (IPC4761 type VII) VIAS RESIN FILLED AND CU CAPPED (IPC4761 type VII) 2 STEPS OF COPPER REDUCTION

REDUCTION
ANNULAR RING 25um
MIN. COPPER TO COPPER

DISTANCE





